



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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**WITCOM**

A member of Wittenburg Group

Your partner in speciality engineering plastics compounds

**Preliminary Data Sheet Witcom PLA-2014/207**

Copper filled PLA

Latest revision: May 2015

Properties	Test methods	Units	Witcom PLA-2014/207
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**Physical properties**

Specific gravity	ISO 1183	g/cm <sup>3</sup>	4,0
Water absorption at saturation, 23 °C	ISO 62	%	1,8
Humidity absorption, 23 °C/50 % r.h.	ISO 62	%	0,3
Mould shrinkage (flow direction, 3 mm)	ISO 2577	%	0,15 - 0,35

**Mechanical properties**

Tensile strength (max.)	ISO 527	MPa	25
Elongation at break	ISO 527	%	3 – 10
Flexural strength	ISO 178	MPa	40
Flexural modulus	ISO 178	GPa	7,0
IZOD impact strength, notched	ISO 180/1eA	kJ/m <sup>2</sup>	5,5
IZOD impact strength, unnotched	ISO 180/1eU	kJ/m <sup>2</sup>	10

**Thermal properties**

Heat distortion temperature (1,81 MPa)	ISO 75	°C	-
Relative temperature index, 3 mm, with impact	UL 746B	°C	-
Coefficient of linear thermal expansion	ISO 11359	K·1·10 <sup>-5</sup>	-

**Flammability**

Burning behaviour	IEC 60695-11-10	-	HB @ 3,2 mm
UL recognition	UL94	-	-

**Electrical properties**

Surface resistivity	ASTM D257	Ω/sq	10 <sup>11</sup>
Comparative tracking index	IEC 60112	V	-
Glow wire rating, 1,6 mm	IEC 695-2-1	°C	-

**Processing conditions (injection moulding)**

Drying conditions (dehumidifying drier)	: 4 Hours @ 60 °C
Maximum allowable moisture content	: 0,05 %
Melt temperature	: 160 - 230 °C
Mould temperature	: 20 - 60 °C
Screw speed	: 0,1 - 0,2 m/s
Back pressure	: 0 - 1,0 MPa
Injection pressure	: Keep to a minimum
Injection speed	: Fast ram speed
Hold pressure	: Keep to a minimum

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